

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

- 1-15 (cancelled)
16. (original) A ball film for fabricating and/or testing integrated circuits, comprising:  
a thin film comprising a plurality of slots; and  
a plurality of metal balls each movably contained within a respective one of the plurality of slots.
17. (original) The ball film of Claim 16, wherein the slots are spherically shaped.
18. (original) The ball film of Claim 16, wherein the thin film is formed from two separate thin films of material.
19. (original) The ball film of Claim 16, wherein the thin film is formed from polyimide.
20. (original) The ball film of Claim 16, wherein the metal balls are formed from solder.
21. (original) The ball film of Claim 16, wherein the thin film comprises a thickness of between 0.01 mm and 0.4 mm.
22. (original) The ball film of Claim 16, wherein the metal balls each have a diameter of between 0.1 mm and 0.5 mm.
- 23-28 (cancelled)